

LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DWN	APVD
		F3		REVISED PER ECO-18-008086	24MAY2018	IT	SH

1. MATERIAL:
 CAGE - 0.25mm THICK NICKEL SILVER ALLOY
 HEATSINK - ALUMINUM
 HEATSINK CLIP - STAINLESS STEEL
 EMI SPRING(S) - COPPER ALLOY

2. FINISH:
 HEATSINK - ELECTROLESS NICKEL
 HEATSINK CLIP - PASSIVATE
 EMI SPRING(S) - 0.8um MIN MATTE TIN OVER 0.8um MIN NICKEL,
 NON-PLATED EDGES PERMISSIBLE.

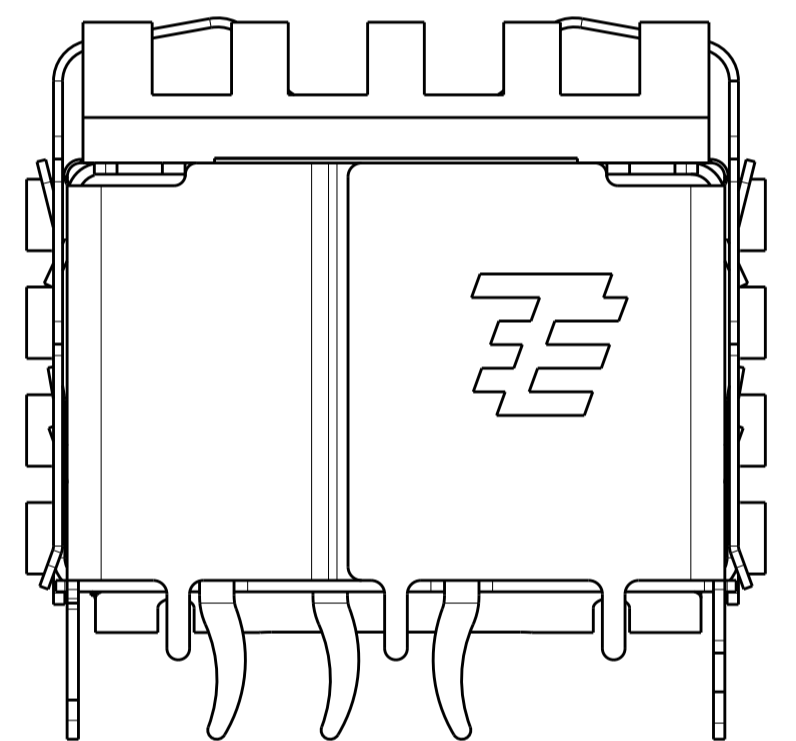
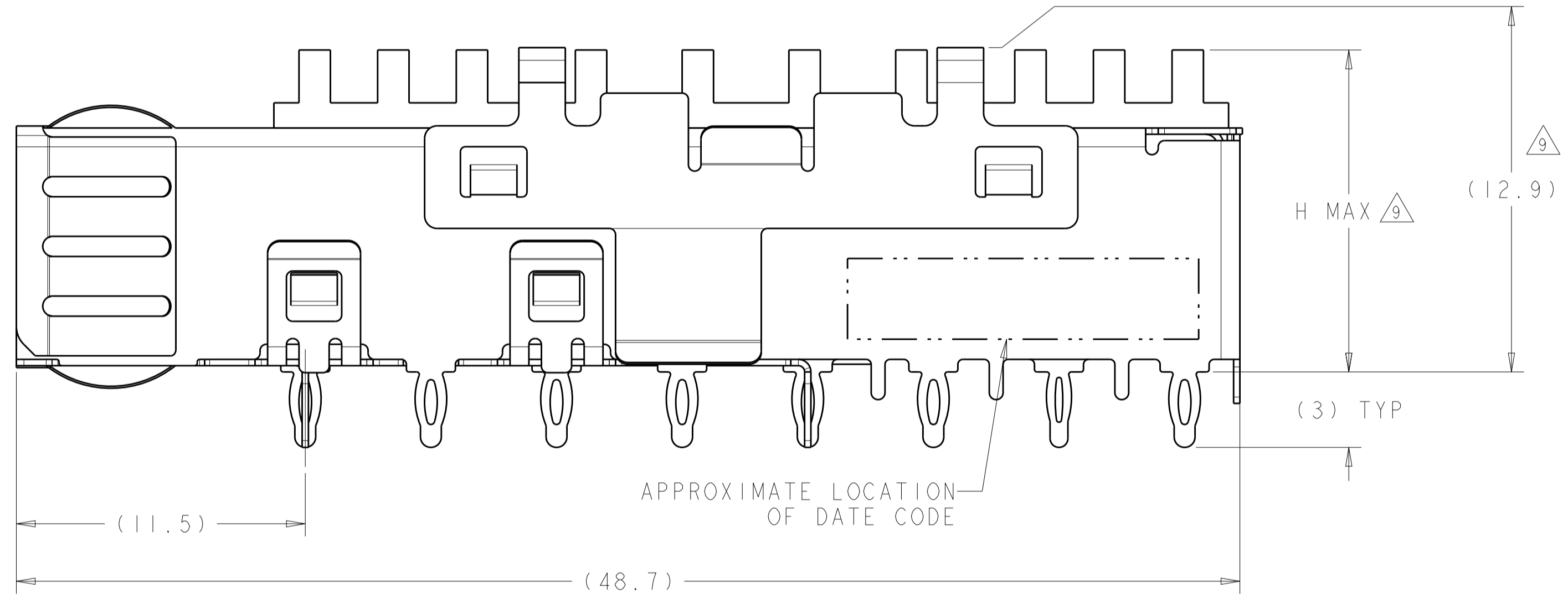
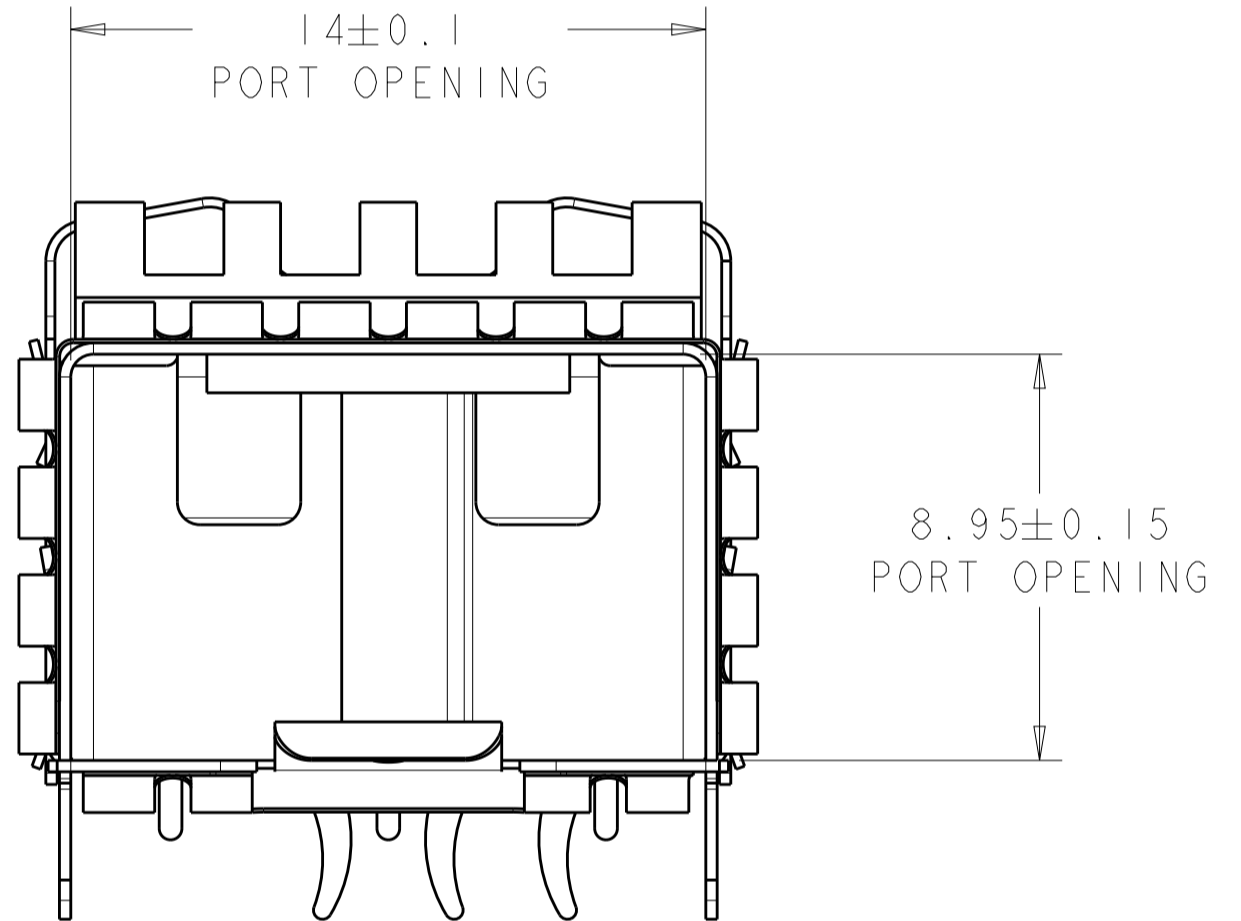
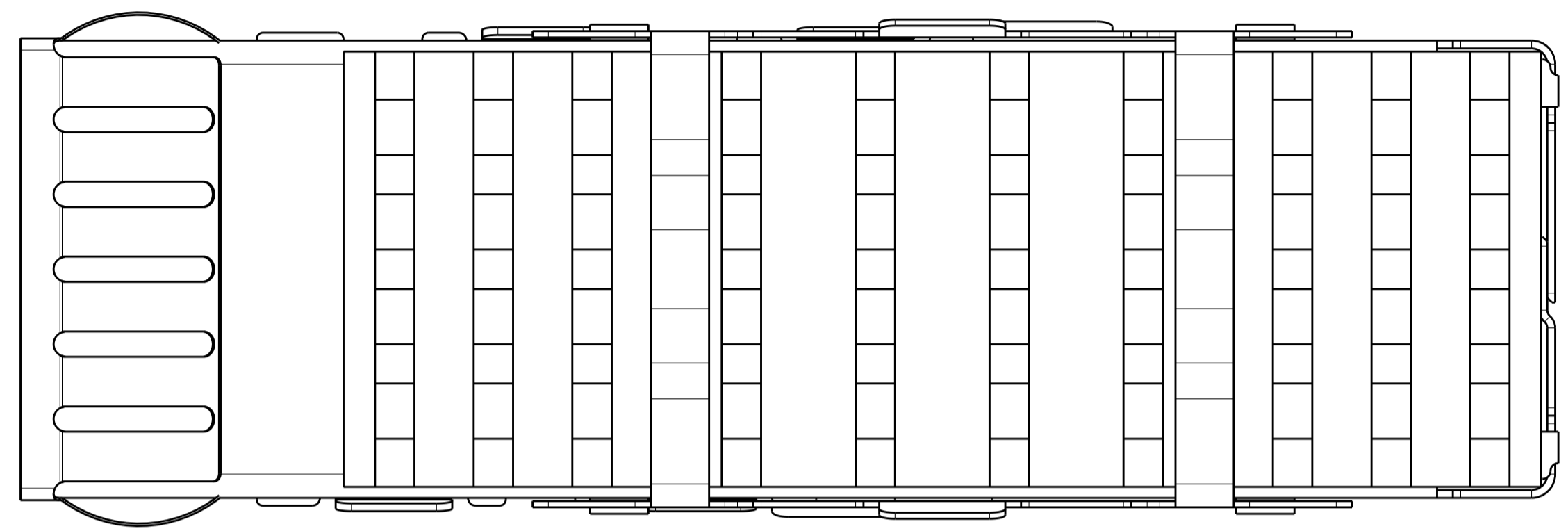
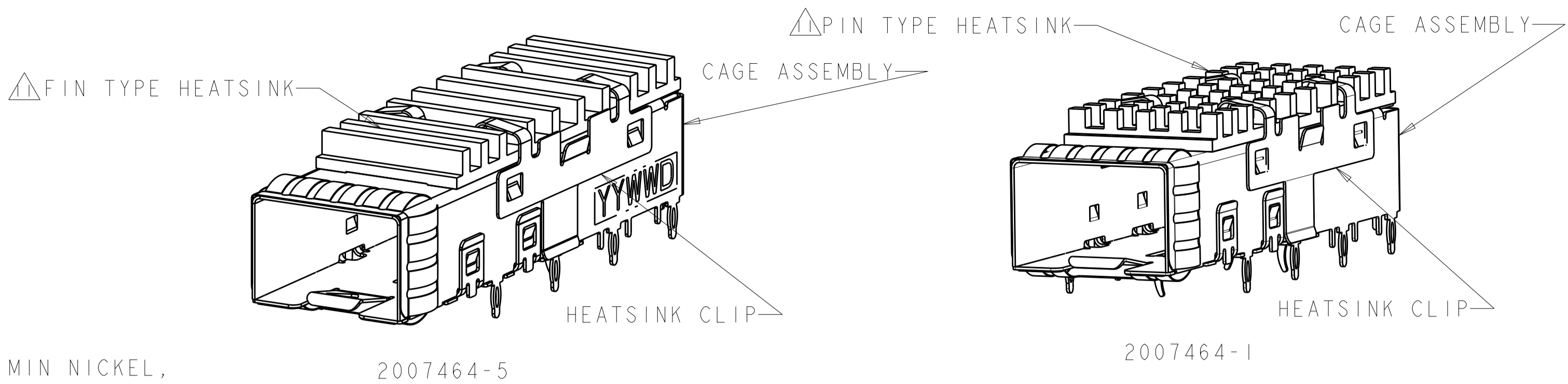
3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.

4. PADS AND VIAS CHASSIS GROUND.

5. DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.

6. MINIMUM PC BOARD THICKNESS:
 SINGLE SIDED = 1.50mm
 DOUBLE SIDED = 3.00mm

7. REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR
 RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.



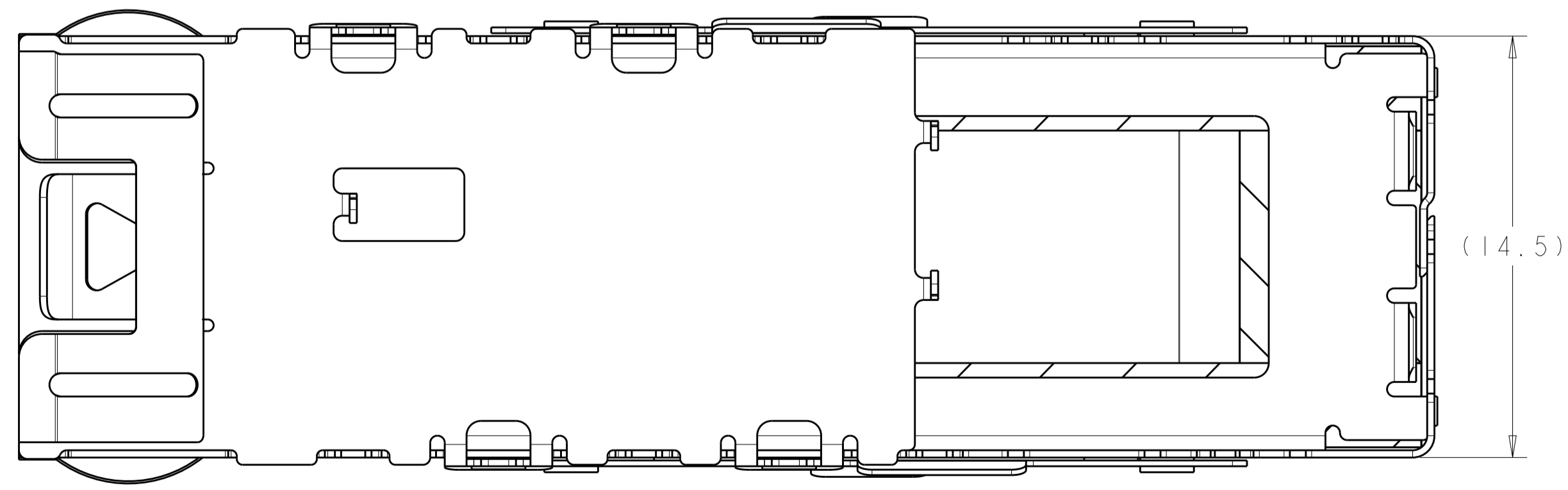
8. REFERENCE APPLICATION SPEC. 114-13120, HOLE C, FOR
 RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.

9. DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE.

10. CAGE ASSEMBLY, HEATSINK CLIP AND HEATSINK SHIPPED
 ASSEMBLED.

11. HEAT SINK REFERENCE PART NUMBERS:
 1829903-2 = 4.2 HIGH - PCI, PIN TYPE
 1829904-2 = 6.5 HIGH - SAN, PIN TYPE
 1829905-2 = 13.5 HIGH - NETWORKING, PIN TYPE
 2170426-4 = 4.2 HIGH - PCI, PIN TYPE
 2170427-4 = 6.5 HIGH - SAN, PIN TYPE
 2170428-4 = 13.5 HIGH - NETWORKING, PIN TYPE

12. REMOVED



DESCRIPTION	H MAX	APPLICATION	PART NUMBER
W/O INSULATING TAPE	13.5	PCI	2007464-9
W/ INSULATING TAPE	22.8	NETWORKING	2007464-8
W/O INSULATING TAPE	22.8	NETWORKING	2007464-7
W/O INSULATING TAPE	15.8	SAN	2007464-6
W/O INSULATING TAPE	13.5	PCI	2007464-5
W/ INSULATING TAPE	22.8	NETWORKING	2007464-4
W/O INSULATING TAPE	22.8	NETWORKING	2007464-3
W/O INSULATING TAPE	15.8	SAN	2007464-2
W/O INSULATING TAPE	13.5	PCI	2007464-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	±0.1
1 PLC	±0.1
2 PLC	±0.1
3 PLC	±0.05
4 PLC	±0.05
ANGLES	±0.05

MATERIAL: FINISH:

Customer Drawing

APPROVED:

DATE: 20NOV2007

NAME: SFP+ 1X1 CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK

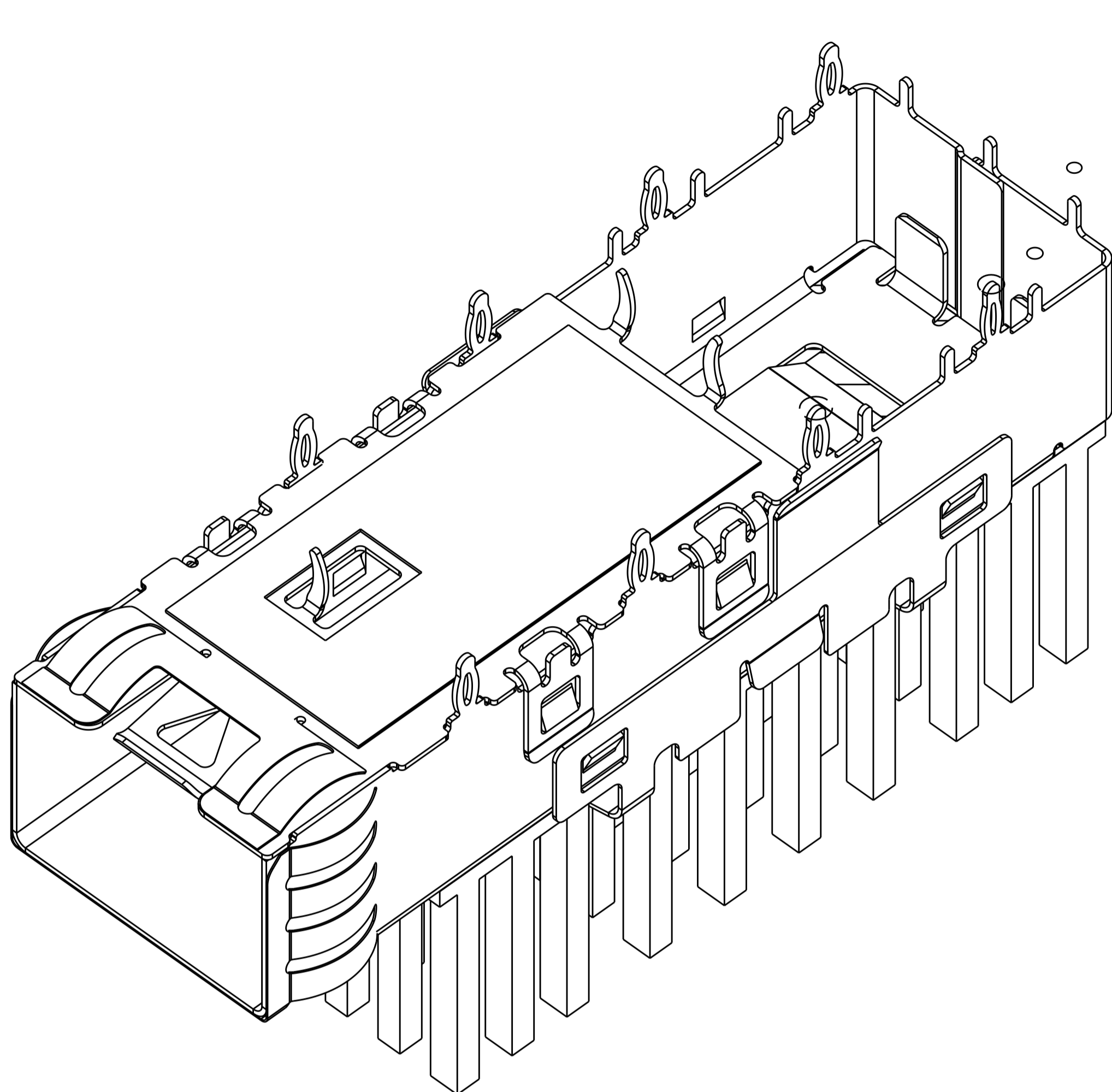
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SCALE: 6:1

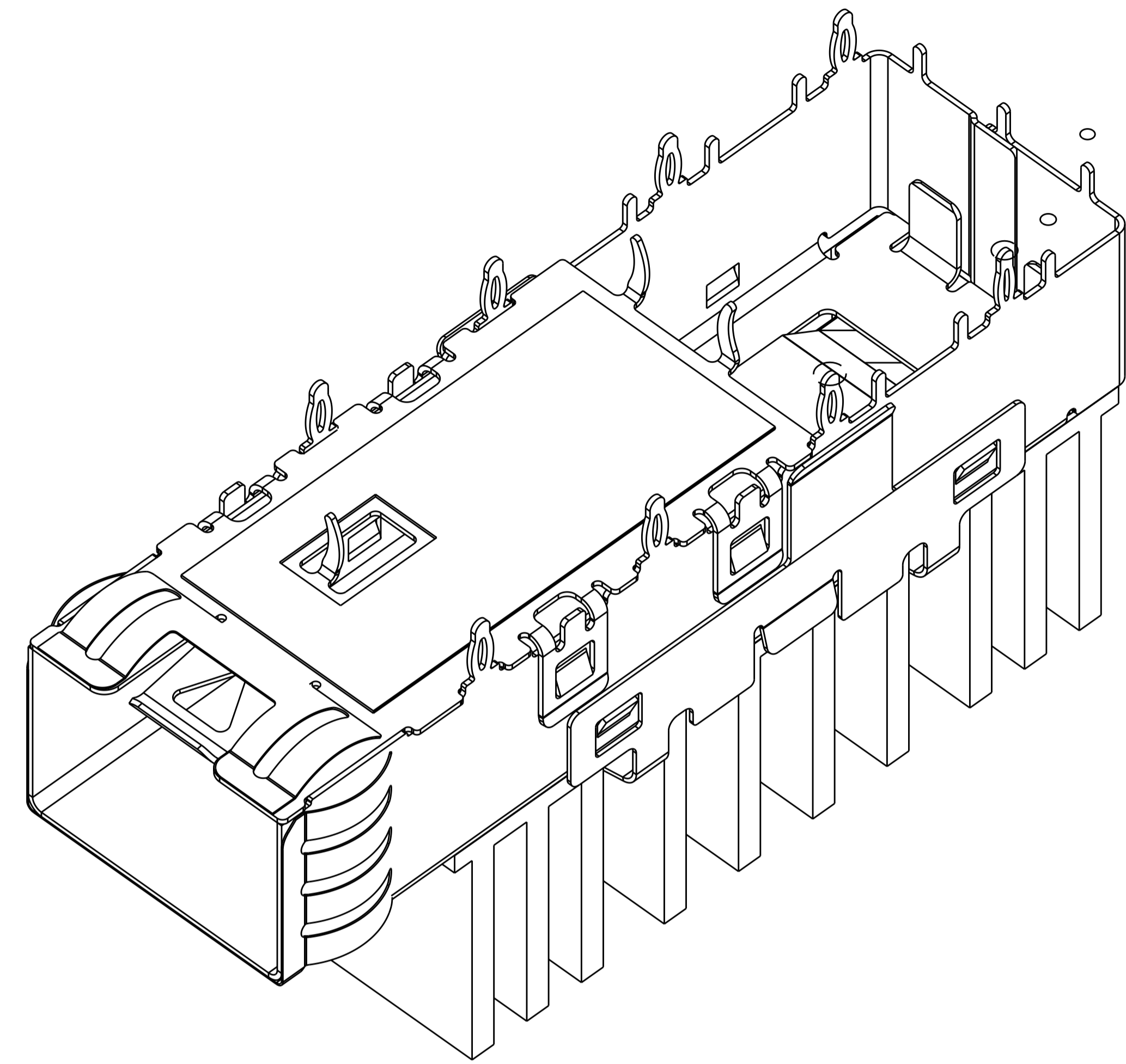
SHEET 1 OF 4

REV: F3

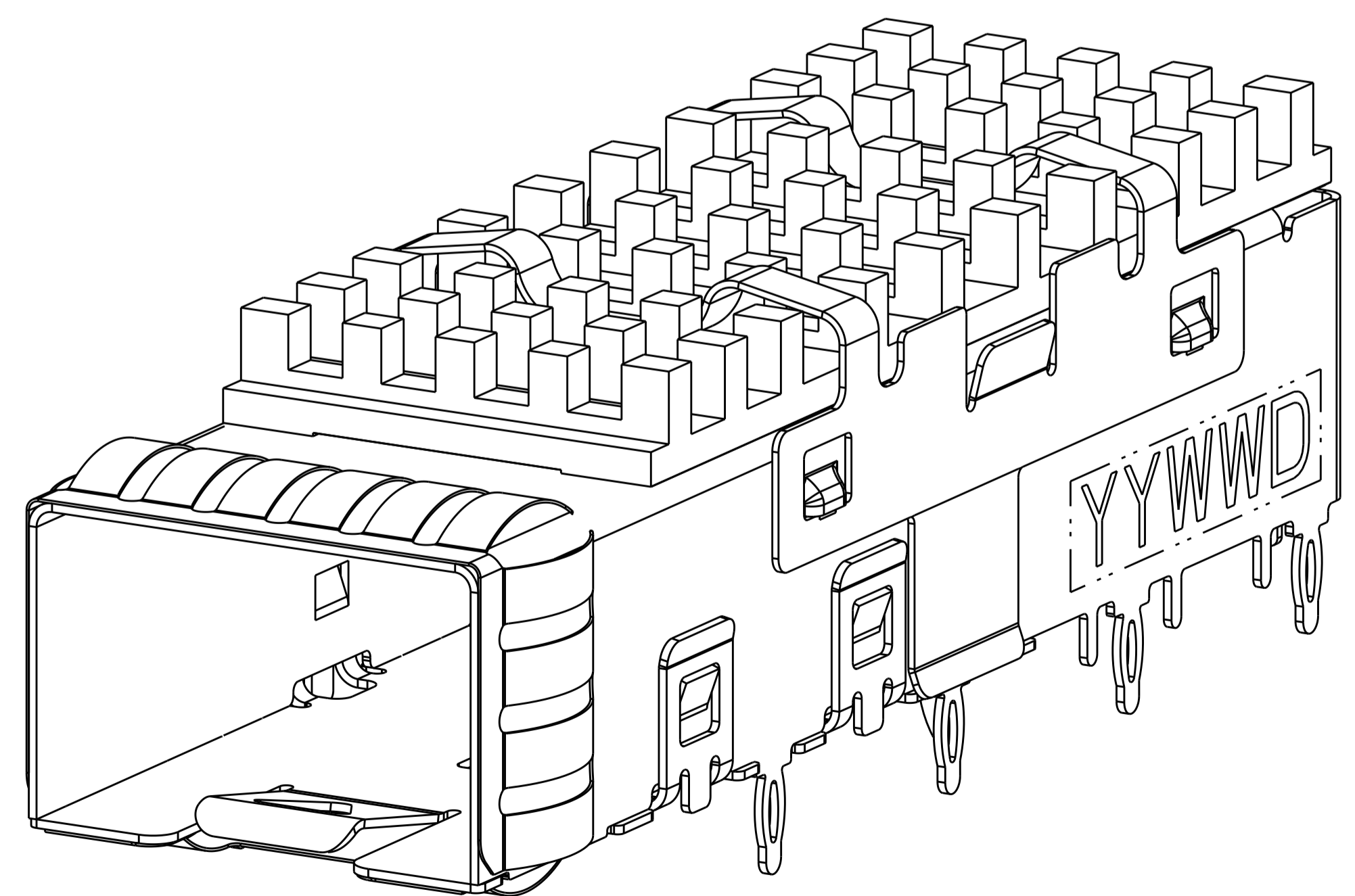
LOC	DIST	REVISIONS			
P	LYR	DESCRIPTION	DATE	DMN	APVD
GP	00	SEE SHEET 1			




2007464-4 AS SHOWN WITH INSULATING TAPE, PIN TYPE HEAT SINK
 2007464-1, 2, 3 WITHOUT INSULATING TAPE, TAPE, PIN TYPE HEAT SINK



2007464-8 AS SHOWN WITH INSULATING TAPE, WITH FIN TYPE HEAT SINK
 2007464-5, 6, 7 WITHOUT INSULATING TAPE, WITH FIN TYPE HEAT SINK

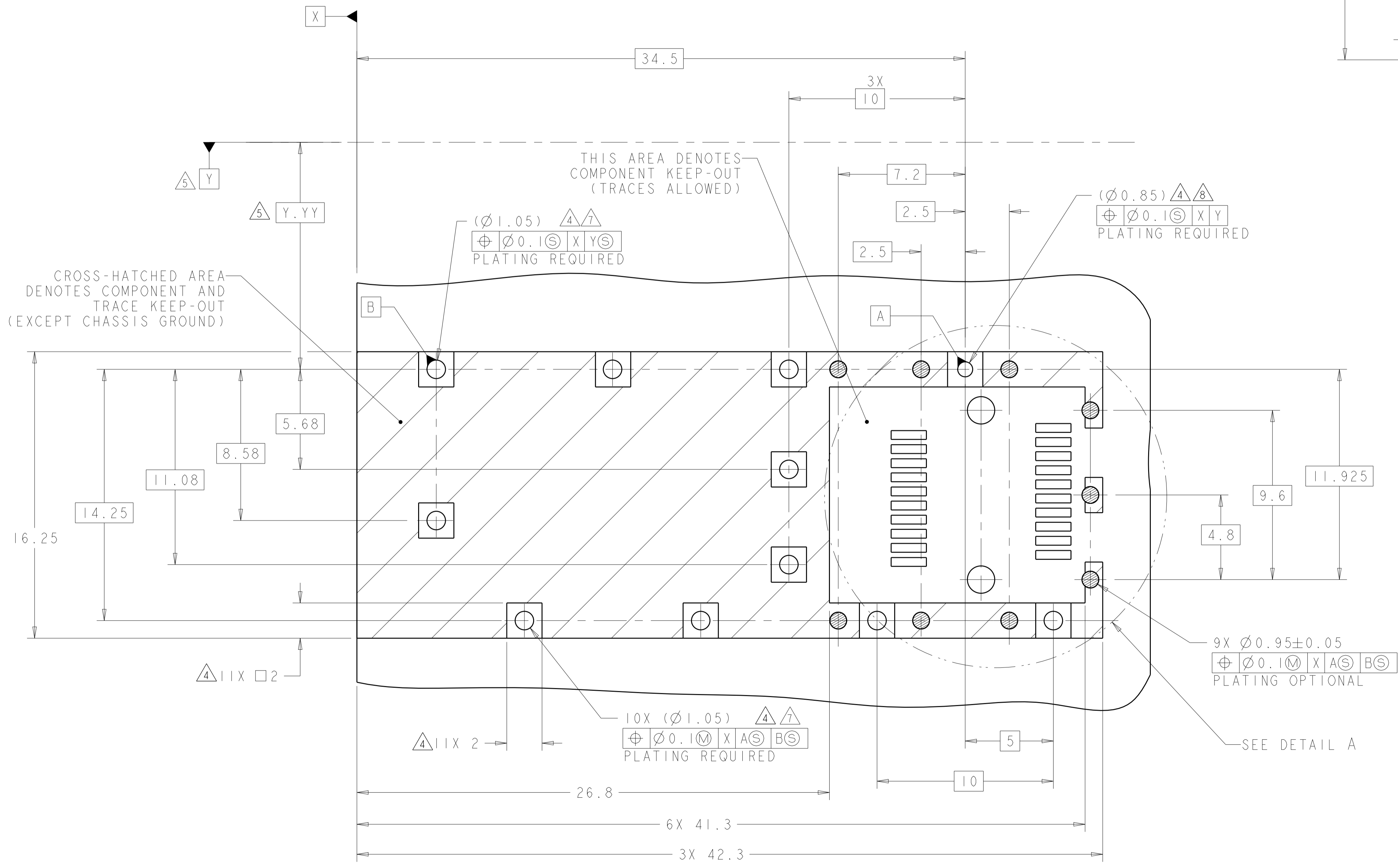
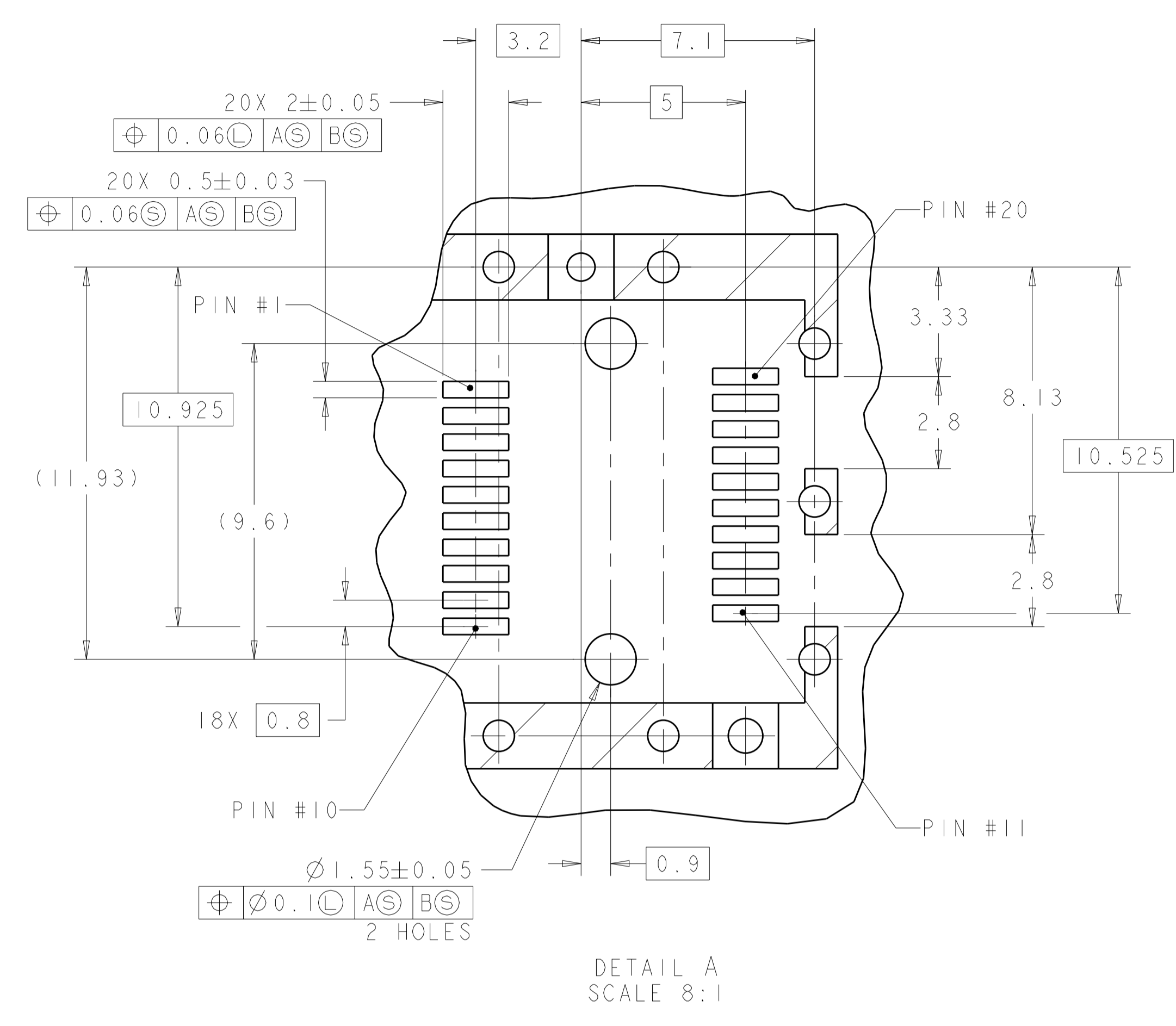
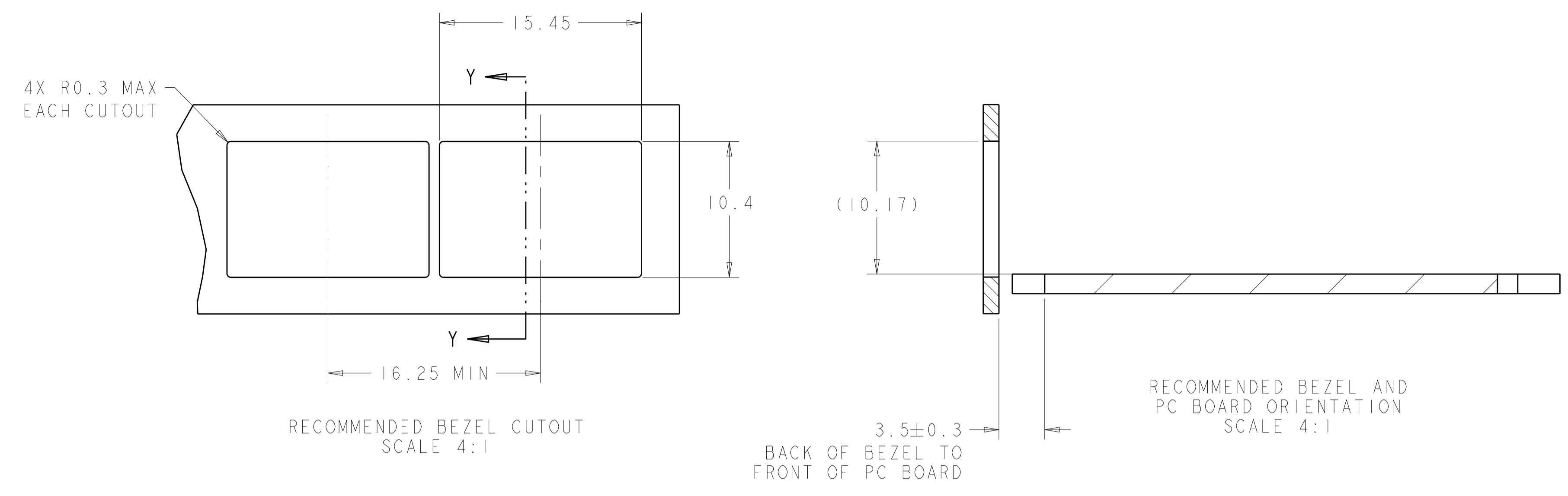


2007464-9 AS SHOWN

THIS DRAWING IS A CONTROLLED DOCUMENT.		DMN Z.M.REAM 20NOV2007	 TE Connectivity
DIMENSIONS:		CHK M.R.SCHMITZ 20NOV2007	
mm		APVD R.H.WERTZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.05 4 PLC ±0.05 ANGLES ±0.05		NAME SFP+ 1X1 CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120 WEIGHT -	
MATERIAL		FINISH	SIZE CAGE CODE DRAWING NO RESTRICTED TO A100779C=2007464 Customer Drawing SCALE 2 SHEET 2 OF 4 REV F3

LOC	DIST	REV	DATE	BY	APPV
GP	00				

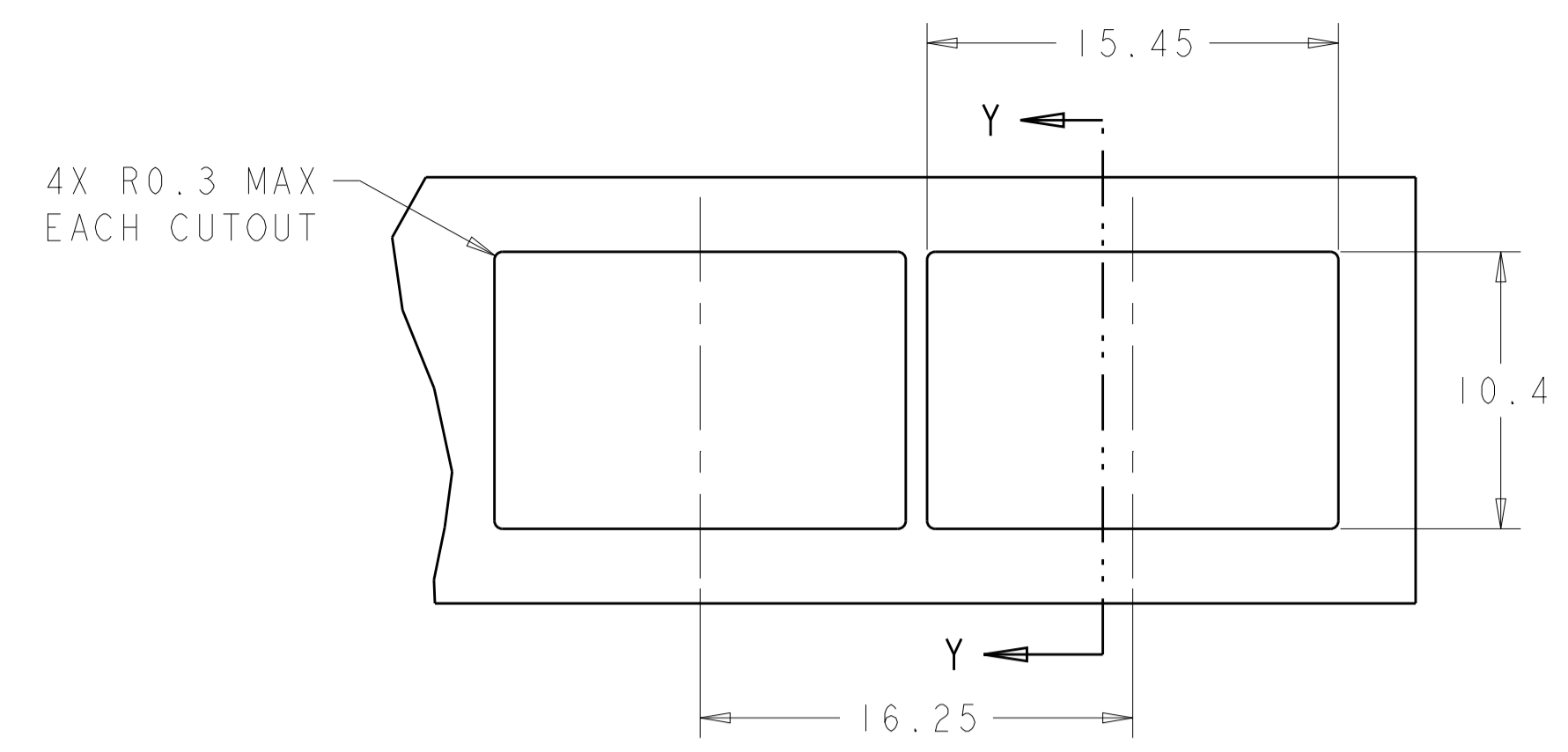
REVISIONS		DATE	BY	APPV
1	SEE SHEET 1			



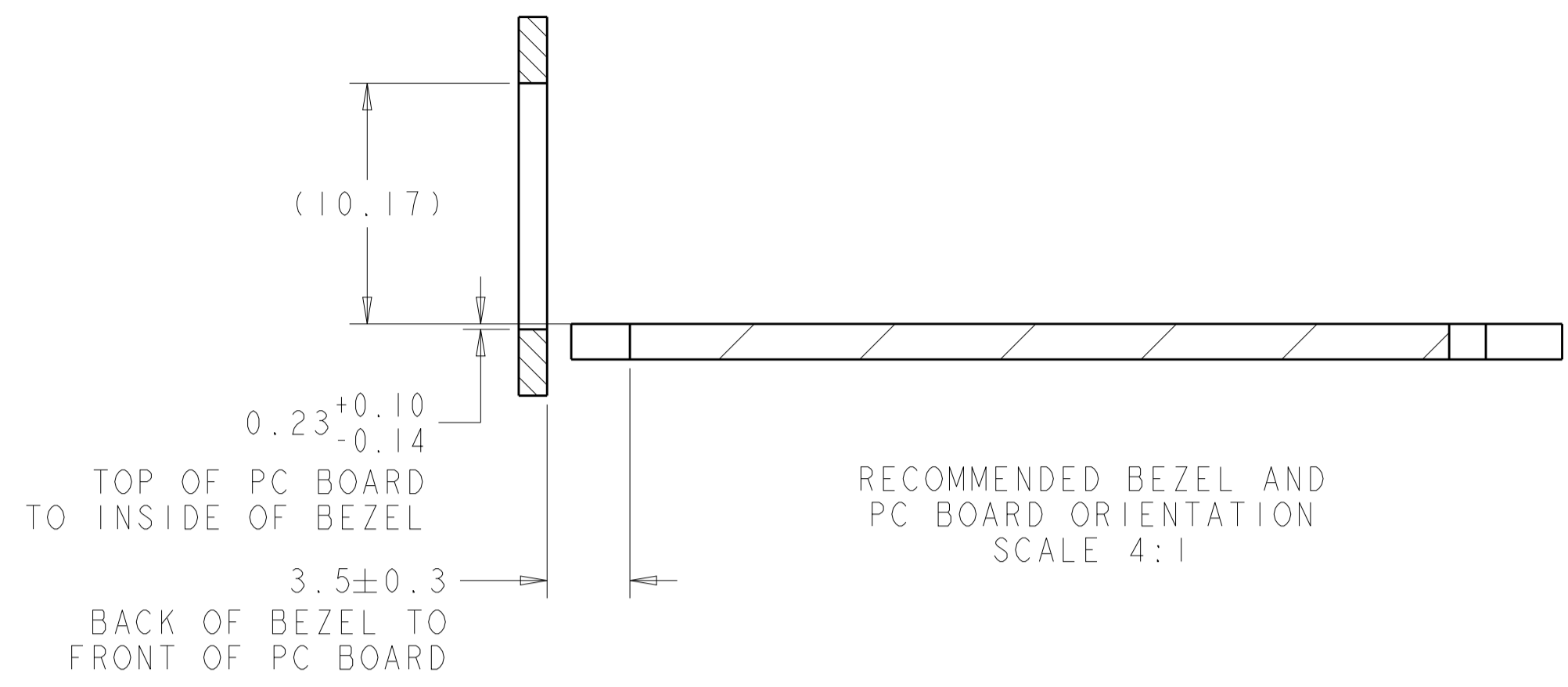
RECOMMENDED PCB LAYOUT SCALE 7:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: Z.M. REAM 20NOV2007	TE Connectivity
DIMENSIONS: mm		CHK: M.R. SCHMITZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: B.H. WERTZ 20NOV2007	NAME: SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC	±0.1	PRODUCT SPEC	SIZE: CAGE CODE DRAWING NO
1 PLC	±0.1	108-2364	RESTRICTED TO
2 PLC	±0.1	APPLICATION SPEC	A100779C=2007464
3 PLC	±0.05	114-13120	SCALE 2 SHEET 3 OF 4 REV F3
4 PLC	±0.05	WEIGHT	
ANGLES	±0.05	Customer Drawing	
MATERIAL	FINISH		

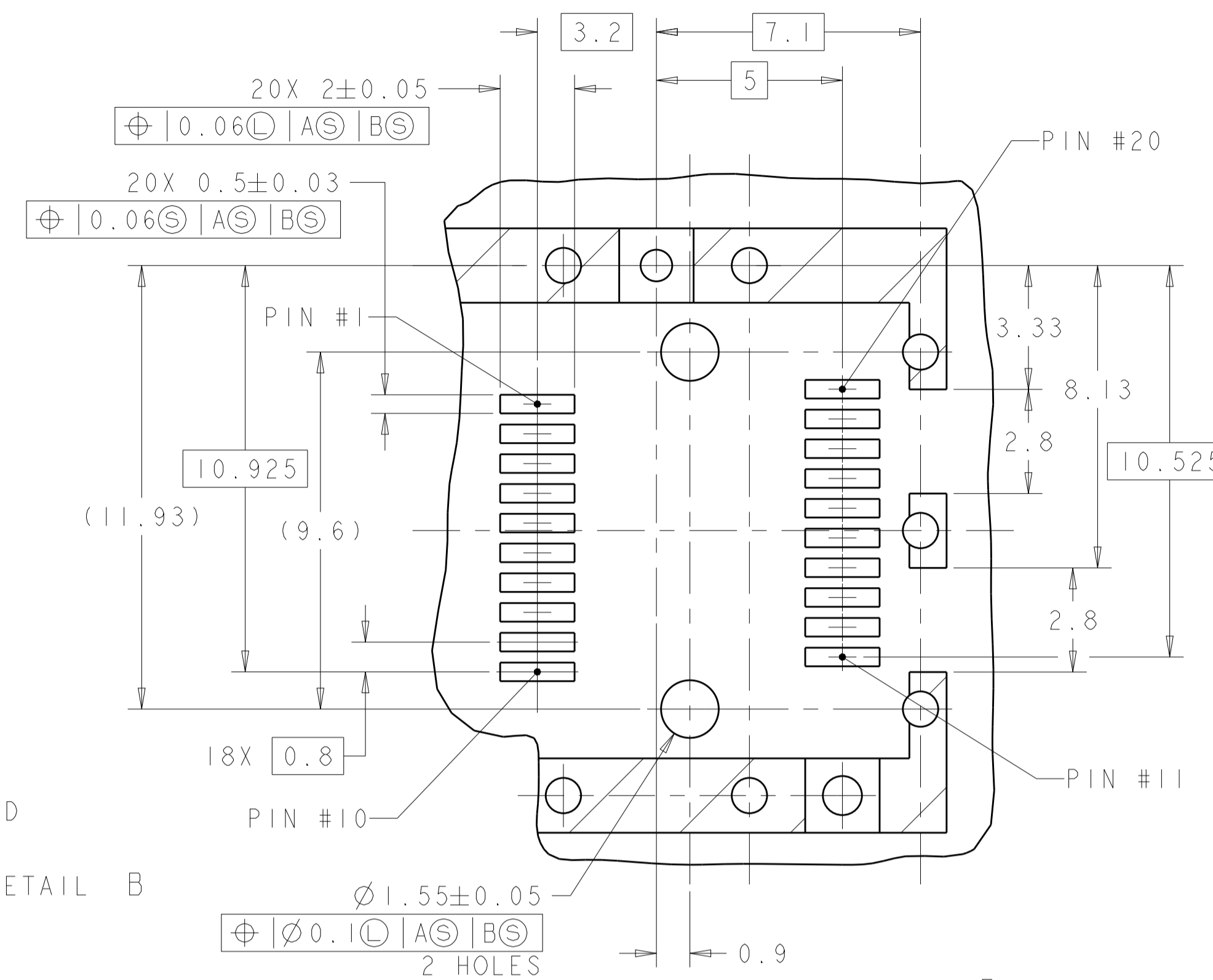
LOC	DIST	REV	DATE	APPD	APVD
GP	00				
		REVISIONS			
		DESCRIPTION	DATE	OWN	APVD
		SEE SHEET 1			



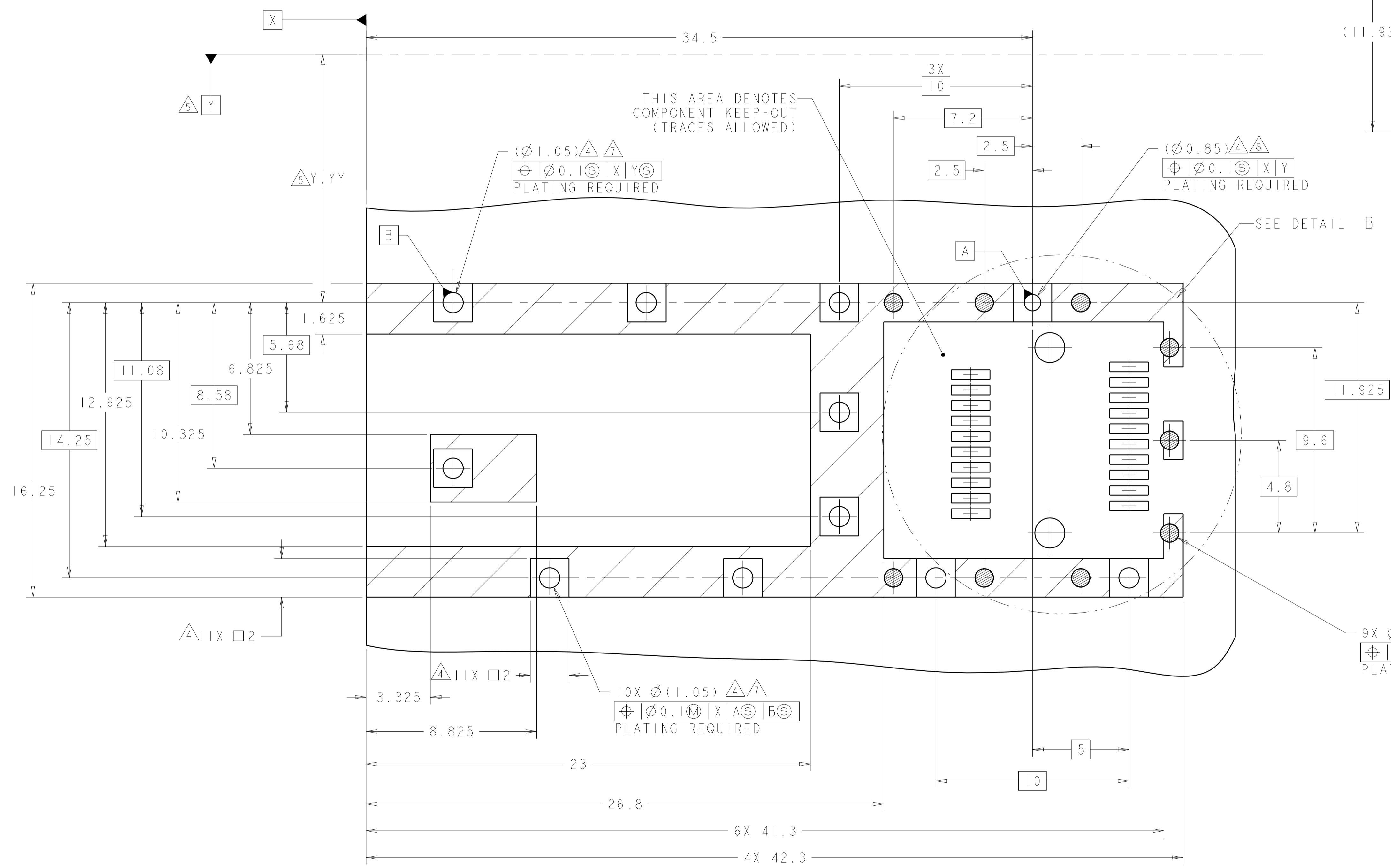
RECOMMENDED BEZEL CUTOUT
SCALE 4:1



TOP OF PC BOARD TO INSIDE OF BEZEL
BACK OF BEZEL TO FRONT OF PC BOARD
RECOMMENDED BEZEL AND PC BOARD ORIENTATION
SCALE 4:1



DETAIL B
SCALE 8:1



RECOMMENDED PCB LAYOUT FOR WITH INSULATING TAPE PART
SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: Z.M.BEAM 20NOV2007	TE Connectivity
DIMENSIONS: mm		CHK: M.R.SCHMITZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: B.H.WERTZ 20NOV2007	NAME: SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC ±0.1		PRODUCT SPEC: 108-2364	SIZE: A100779
1 PLC ±0.1		APPLICATION SPEC: 114-13120	SCALE: 2
2 PLC ±0.1		WEIGHT: -	SHEET: 4 OF 4
3 PLC ±0.05		Customer Drawing	REV: F3
4 PLC ±0.05			
ANGLES ±0.05			
FINISH: -			

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Authorized Distributor

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[2007464-2](#)